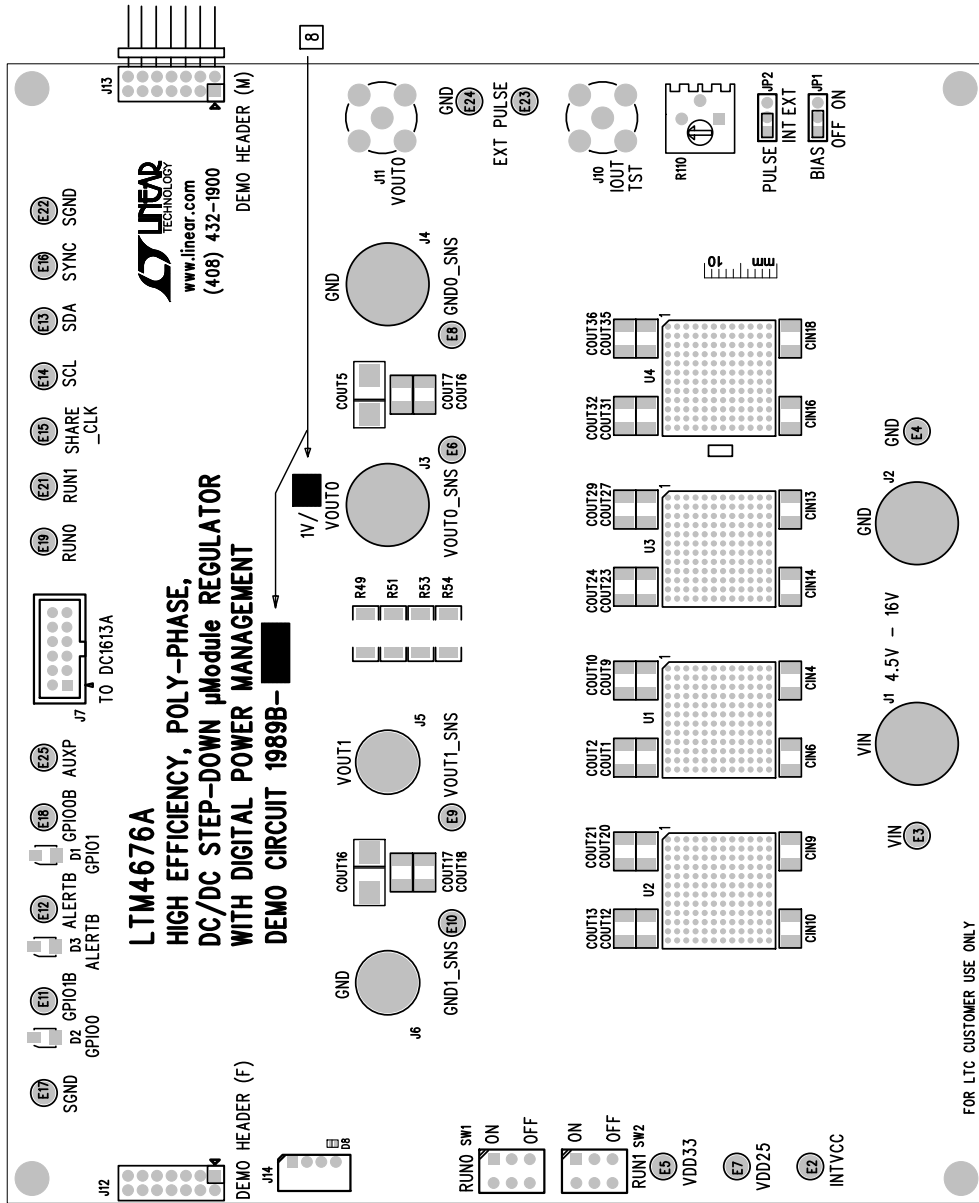
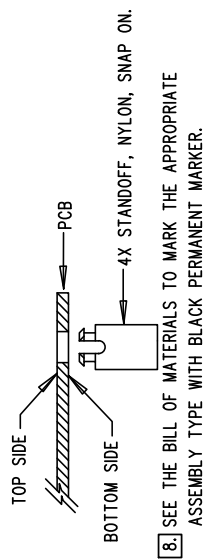


REVISION HISTORY			
ECO REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	JIAN L.
			10-15-15



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANALIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



BOARD ASSEMBLY

ASSY	VOUT0
-A	1V/50A
-B	1V/75A
-C	1V/100A

APPROVALS		LINEAR TECHNOLOGY	
PCB DES.	HZ	1830 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 WWW.LINEAR.COM LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
APP ENG.	JIAN L.	TITLE: TOP ASSEMBLY DRAWING	
		HIGH EFFICIENCY, POLY-PHASE, DC/DC STEP-DOWN μModule REGULATOR WITH DIGITAL POWER MANAGEMENT	
		SIZE	IC NO. LTM4676AEY
		N/A	DEMO CIRCUIT 1989B-A/B/C
		SCALE = NONE	FILENAME: DC1989B-1.PCB
		SHT 1 OF 2	